



Bond Pad Metallization Change on SLC/MLC NAND for Non-Automotive Products

PCN: 33263

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Type: Manufacturing Process Change

Description: Micron will convert the bond pad metallization of SLC/MLC NAND devices at Fab 6 to align with other products at this site. Other DRAM/NAND technologies at Fab 6 use Al bond pad process and is proven to be more robust. The change will not impact the final packaged product. Micron has complete traceability via Lot ID number, Sales Order number, or Purchase Order number etc.

After the process implementation date, Micron reserves the right to ship either ALM2 or NiPd manufactured until the NiPd inventory has been depleted.

Was	IS	
Layers:	Layers:	Affected DIDs
Metal 2: Cu + Ni/Pd (Plating)	Metal 2: Al (Sputter)	M72A, M73A, L73A, L72A, M68M, M60A, M68A, M69A
Polyimide	Polyimide	M72A, M73A, L73A
Non-Polyimide	Polyimide	L72A, M60A, M68A, M68M, M69A

Reason: Improved Product Quality and Reliability, Manufacturing Efficiency

Product Affected: SLC/MLC NAND

Affected Micron Part Number Component	Recommended Replacement	Customer Part Number
MT29F128G08AJAAWP-ITZ:A		
MT29F128G08AKCABH2-10ITZ:A		
MT29F128G08AMCABH2-10ITZ:A		
MT29F16G08ABACAWP-ITZ:C		557-1835-2-ND, ?
MT29F16G08ABCCBH1-10ITZ:C		557-1837-2-ND
MT29F16G08AJADAWP-IT:D		557-1838-2-ND
MT29F16G08CBACAWP:C		
MT29F1G08ABADAH4-IT:D		557-1597-ND
MT29F1G08ABADAH4-ITX:D		
MT29F1G08ABADAWP-ITX:D		557-1840-2-ND
MT29F1G08ABAEAH4:E		557-1657-2-ND
MT29F1G08ABAEAH4-ITX:E		
MT29F1G08ABAEAWP:E		557-1659-2-ND, ?
MT29F1G08ABAEAWP-IT:E		557-1658-2-ND, ?
MT29F1G08ABAEAWP-ITX:E		557-1844-2-ND
MT29F1G08ABBDAH4-ITX:D		
MT29F1G08ABBEAH4-ITX:E		
MT29F1G16ABBDAH4-ITX:D		
MT29F1G16ABBDAH4-IT:D		557-1846-2-ND
MT29F1G16ABBEAH4-ITX:E		557-1848-2-ND
MT29F256G08AUCABH3-10ITZ:A		
MT29F2G08ABAEAH4:E		557-1486-2-ND
MT29F2G08ABAEAH4-IT:E		557-1600-ND, ?, 557-1852-2-ND
MT29F2G08ABAEAH4-ITX:E		557-1853-2-ND
MT29F2G08ABAEAWP:E		557-1487-2-ND, ?

MT29F2G08ABAEAWP-IT:E		?, 557-1488-2-ND
MT29F2G08ABAEAWP-ITX:E		557-1856-2-ND, ?
MT29F2G08ABBEAH4-IT:E		557-1858-2-ND
MT29F2G08ABBEAH4-ITX:E		557-1859-2-ND
MT29F2G08ABBEAHC-IT:E		557-1860-2-ND
MT29F32G08ABAAAWP-ITZ:A		
MT29F32G08ABCABH1-10ITZ:A		?
MT29F32G08CBACAWP-Z:C		557-1864-2-ND, ?
MT29F4G08ABADAH4:D		557-1868-2-ND
MT29F4G08ABADAH4-ITX:D		
MT29F4G08ABADAWP:D		?, 557-1458-2-ND
MT29F4G08ABADAWP-IT:D		557-1541-2-ND, ?, MT29F4G08ABADAWP-IT:D-ND
MT29F4G08ABADAWP-ITX:D		557-1869-2-ND, ?
MT29F4G08ABBDAH4:D		557-1874-2-ND
MT29F4G08ABBDAH4-IT:D		557-1873-2-ND
MT29F4G08ABBDAH4-ITX:D		
MT29F4G08ABBDAH4-IT:D		557-1459-2-ND
MT29F4G16ABBDAH4-IT:D		
MT29F64G08AECABH1-10ITZ:A		
MT29F64G08AFAAAWP-ITZ:A		557-1675-2-ND
MT29F8G08ADADAH4-IT:D		557-1601-ND, ?
MT29F8G16ADADAH4-IT:D		557-1883-2-ND

*Materials that have been ordered are in **bold**.

Method of Identification:	none
Micron Sites Affected:	Fab 6 - US
Sample Available:	2019-07-31
Qual Data Available:	2019-05-31
Product Ship Date:	2020-01-31

NOTE: Per JEDEC Standard JESD46-C Section 3.2.3; lack of acknowledgment of this PCN within 30 days constitutes acceptance of change.

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Attachments

There are no attachments on this PCN